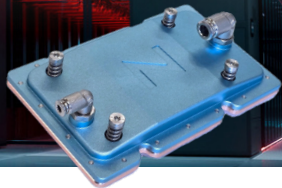


ZutaCore® HyperCool® - SXM6 B300 Cold Plate

High-performance two-phase liquid cooling cold plate for AI/GPU servers.

Technical Datasheet
June 2026



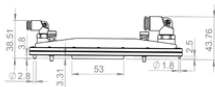
Purpose-built for NVIDIA HGX™ B300 platforms, the ZutaCore® HyperCool® B300 Cold Plate delivers industry-leading thermal performance with ZutaCore's patented waterless two-phase direct-to-chip cooling technology.

Designed for production AI infrastructure, it enables sustained performance, higher rack densities and greater energy efficiency without introducing water inside the server.

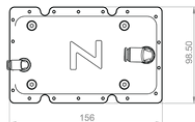
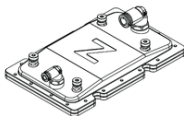
Built for the next generation of AI, the ZutaCore® HyperCool® B300 Cold Plate removes thermal barriers to maximise compute performance while reducing cooling power consumption.

Designed for High-Density Enterprise AI

- NVIDIA HGX™ B300 AI platforms
- AI factories and hyperscale infrastructure
- High-density GPU & accelerated computing clusters
- HPC and Enterprise AI deployments
- Liquid-cooled data centres



all dimensions in mm



Key Features & Benefits

Up to 1,200W Cooling Capacity

Supports today's highest-power AI processors while providing headroom for future silicon generations.

Waterless Two-Phase Cooling

Eliminates water from inside the server using a closed-loop dielectric cooling architecture for enhanced reliability.

Instant Heat Removal

Pool boiling technology removes heat immediately at the chip, maintaining consistent thermal performance under demanding AI workloads.

Optimised for NVIDIA HGX™ B300

Purpose-built for HGX B300 platforms with a precision-engineered form factor and complete server loop compatibility.

Lower Pumping Power

Ultra-low flow requirements reduce pumping energy and simplify liquid cooling infrastructure.

Production-Ready Design

Engineered for fast integration, long-term reliability and simplified serviceability across enterprise and hyperscale deployments.

Technical Specifications

Performance	
Cooling Capacity	1,200 W
Typical Operating Pressure	Vapor line: ~1.2-bar gauge; Liquid Line: ~2.2-bar gauge
Wetted Materials	Aluminum housing; copper base; neoprene gasket
Environmental	
Operating Temperature	-20 to 50°C
Storage Conditions	-40 to 90°C, 0 to 99% RH (non-condensing)
Physical Characteristics	
Dimensions (WxHxL)	98.5 mm x 43.76 mm x 156 mm
Liquid Inlet	4 mm (OD) push-in connector
Vapor Inlet	8 mm (OD) push-in connector

The Two-Phase Advantage

Two-phase cooling leverages evaporation-based heat transfer to remove high thermal loads efficiently and consistently.

- High heat transfer efficiency
- Stable temperature control under sustained load
- Reduced thermal stress on GPU and memory components

Integration

Designed for seamless integration into NVIDIA HGX™ B300 server platforms, the ZutaCore® HyperCool® B300 Cold Plate fits within existing OEM and ODM architectures. Its compact, production-ready design simplifies deployment while enabling scalable liquid-cooled AI infrastructure.